

Erdal Uzunlar

List of Publications by Year in Descending Order

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

15
papers

171
citations

9
h-index

13
g-index

15
ext. papers

205
ext. citations

3.2
avg, IF

3
L-index

#	Paper	IF	Citations
15	A Promising Catalyst for the Dehydrogenation of Perhydro-Dibenzyltoluene: Pt/Al ₂ O ₃ Prepared by Supercritical CO ₂ Deposition. <i>Catalysts</i> , 2022 , 12, 489	4	0
14	Review Supercritical Deposition: A Powerful Technique for Synthesis of Functional Materials for Electrochemical Energy Conversion and Storage. <i>Journal of the Electrochemical Society</i> , 2020 , 167, 054510	3.9	11
13	Investigation of the effect of gel properties on supercritical drying kinetics of ionotropic alginate gel particles. <i>Journal of Supercritical Fluids</i> , 2019 , 152, 104571	4.2	7
12	Investigation of kinetics of supercritical drying of alginate algogel particles. <i>Journal of Supercritical Fluids</i> , 2019 , 146, 78-88	4.2	9
11	Metallo-organic n-type thermoelectrics: Emphasizing advances in nickel-ethenetetrathiolates. <i>Journal of Applied Polymer Science</i> , 2017 , 134,	2.9	22
10	Decomposable and Template Polymers: Fundamentals and Applications. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2016 , 138,	2	20
9	Size-Compatible, Polymer-Based Air-Gap Formation Processes, and Polymer Residue Analysis for Wafer-Level MEMS Packaging Applications. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2015 , 137,	2	14
8	Airgap Interconnects: Modeling, Optimization, and Benchmarking for Backplane, PCB, and Interposer Applications. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2014 , 4, 1335-1346	1.7	20
7	Low-Cost MEMS Packaging Using Polymer-Based Air-Gaps. <i>ECS Transactions</i> , 2014 , 61, 237-242	1	2
6	Frequency response of microcantilevers immersed in gaseous, liquid, and supercritical carbon dioxide. <i>Journal of Supercritical Fluids</i> , 2013 , 81, 254-264	4.2	10
5	Design and fabrication of ultra low-loss, high-performance 3D chip-chip air-clad interconnect pathway 2013 ,		3
4	Electroless Copper Deposition Using Sn/Ag Catalyst on Epoxy Laminates. <i>Journal of the Electrochemical Society</i> , 2013 , 160, D3237-D3246	3.9	15
3	Design and fabrication of low-loss horizontal and vertical interconnect links using air-clad transmission lines and through silicon vias 2012 ,		10
2	Thermal and photocatalytic stability enhancement mechanism of poly(propylene carbonate) due to Cu(I) impurities. <i>Polymer Degradation and Stability</i> , 2012 , 97, 1829-1837	4.7	6
1	Electroless Deposition of Copper on Organic and Inorganic Substrates Using a Sn/Ag Catalyst. <i>Journal of the Electrochemical Society</i> , 2012 , 159, D386-D392	3.9	22